## CORFIL® 615

## Adhesive

Cytec Industries Inc.

## Message:

CORFIL® 615 potting compound is a low density compound for use as insert or edge filling material in honeycomb sandwich construction. After the curing agent is added, CORFIL 615 remains a thick paste which will not run of its own weight when placed in the desired construction. This thixotropic property is highly convenient because it eliminates the need for molds or other containing devices during the curing period. After CORFIL 615 is cured it will withstand subsequent temperatures up to 350°F (177°C) without becoming fluid or otherwise impairing its use as a structural material. Three curing agents are available to cure the potting compound to a hard, rigid material. These are: Curing Agent "Z" for curing at elevated temperature; Curing Agent "A" for curing at 120°F (49°C); and Curing Agent "DTA" for curing at ambient temperature.

| General Information                      |  |       |
|--|--|-------|
| Features                                 | Good Adhesion                            |       |
|  | High Heat Resistance                     |       |
|  | Low Density                              |       |
|  | Thixotropic                              |       |
|  |  |       |
| Uses                                     | Adhesives                                |       |
|  | Filling Applications                     |       |
|  | Structural Parts                         |       |
|  |  |       |
| Appearance                               | Maroon                                   |       |
| Forms                                    | Paste                                    |       |
| Processing Method                        | Potting                                  |       |
| Physical                                 | Nominal Value                            | Unit  |
| Specific Gravity <sup>1</sup>            | 0.600                                    | g/cm³ |
| Mechanical                               | Nominal Value                            | Unit  |
| Tensile Modulus <sup>2</sup>             | 633                                      | MPa   |
| Compressive Strength <sup>3</sup> (23°C) | 41.4                                     | MPa   |
| Additional Information                   | Nominal Value                            | Unit  |
| Cure Cycle <sup>4</sup> (49°C)           | 16.0                                     | hr    |
| NOTE                                     |  |       |
| 1.                                       | Curing Agent "A" used with CORFIL<br>615 |       |
| 2.                                       | Curing Agent "A" used with CORFIL        |       |
| <b>L</b> .                               |  |       |
| 3.                                       | Curing Agent "A" used with CORFIL<br>615 |       |
| 4.                                       | With 2 hours at room temperature         |       |

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